



Material Content Data Sheet



Sales Product Name		BSC026N04LS		Issued		19. July 2018			
MA#		MA001075576							
Package		PG-TDSON-8-6		Weight*		118.35 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.552	0.47	0.47	4666	4666	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96		
	non noble metal	copper	7440-50-8	37.762	31.91	31.95	319065	319480	
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	382	382	
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		741		
	plastics	epoxy resin	-	6.227	5.26		52611		
	inorganic material	silicondioxide	60676-86-0	37.535	31.71	37.04	317149	370501	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12266	12266	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1399	1399	
solder	noble metal	silver	7440-22-4	0.021	0.02		173		
	non noble metal	tin	7440-31-5	0.016	0.01		139		
	non noble metal	lead	7439-92-1	0.784	0.66	0.69	6624	6936	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
	non noble metal	copper	7440-50-8	11.320	9.56	9.57	95648	95773	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57		
	non noble metal	copper	7440-50-8	22.292	18.84	18.87	188351	188597	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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